

CLAIM AMENDMENTS

This listing of the claims will replace all prior versions and listings of claims in the Application.

1 -21 (Cancelled)

22. (Currently Amended) A method of shielding [[an]] a space radiation shielded integrated circuit device, wherein the space radiation shielded integrated circuit device comprises a plurality of circuit components, and is adapted for use in space, comprising:

forming a first package layer comprising a first circuit package, a copper-tungsten radiation shielding base, a first substrate, a first circuit die, a first lid, whereby the copper-tungsten radiation shielding base shields a bottom portion of the space radiation shielded integrated circuit device against incident radiation ~~first radiation shielding base, a first package and a first circuit die;~~

attaching the first circuit die to the first substrate using cyanate ester;

soldering the first circuit package to the copper-tungsten radiation shielding base, using a high-temperature copper-silver solder;

attaching the first substrate to the first circuit package, using cyanate ester;

soldering the first lid to the first package layer, using a high-temperature gold-tin solder;

forming a second package layer comprising a second substrate, a second circuit package, a second circuit die, a second radiation shielding base, a second package and a second circuit die;

attaching the second circuit die to the second substrate, using cyanate ester

attaching the second substrate to the second circuit package, using cyanate ester, and;

soldering the second package layer to the first package layer using a high-temperature gold-tin solder, thereby forming electrical interconnects, whereby the first package layer and the second package layer are in electrical communication.

coupling a bottom of the first package layer to a top of the second package layer, and

coupling a lid to the first package layer.

23. (Currently Amended) The method of shielding the space radiation shielded integrated circuit device of claim 22 further comprising forming the first lid from a high Z material.

24. (Currently Amended) The method of shielding the space radiation shielded integrated circuit device of claim 22 further comprising forming the [[first]] copper-tungsten radiation shielding base ~~and the second radiation shielding base~~ from a high Z material.

25. (Currently Amended) The method of shielding the space radiation shielded integrated circuit device of claim 22 wherein the first circuit die receives an amount of radiation less than the total dose tolerance of the first circuit die.

26. (Currently Amended) The method of shielding the space radiation shielded integrated circuit device of claim 22 wherein the second circuit die receives an amount of radiation less than the total dose tolerance of the second circuit die.

27 - 50 (Cancelled)